

### 1 Key Message

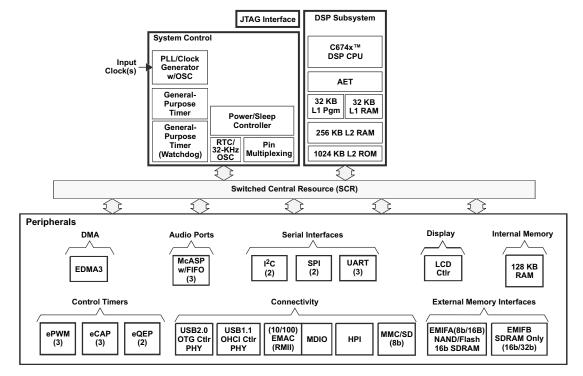
The C674x Floating-point Processor generation combines a new level of performance / precision and dynamic range with high power efficiency and system integration. The C674x processors are completely code compatible with other C67x processors.

### 1.1 Key Features

- Power Management / Power Savings
  - Supports Individual Clock Enable/Disable Control for DSP and Peripherals
  - Real Time Clock (RTC) With Crystal Input, Separate Clock Domain, Separate Power Supply
- 200-, 300-MHz C674x<sup>™</sup> Floating Point VLIW DSP Core
  - 8 Highly Independent Functional Units
  - 64 General-Purpose Registers (32 Bit)
  - Instruction Packing Reduces Code Size
  - Hardware Support for Modulo Loop Operation
  - Protected Mode Operation

- C674x Instruction Set Features
  - Superset of the C67x+™ and C64x+™ ISAs
  - 1600/1200, 2400/1800 C674x MIPS/MFLOPS
  - Byte-Addressable (8-/16-/32-/64-Bit Data)
  - 8-Bit Overflow Protection
  - Bit-Field Extract, Set, Clear
  - Normalization, Saturation, Bit-Counting
  - Compact 16-Bit Instructions
- C674x Two Level Cache Memory Architecture
  - Flexible RAM/Cache Partition (L1 and L2)
- 128K-Byte Internal RAM Shared Memory
- Comprehensive System-Wide Security
- Applications: Range from Professional Audio to Audio Conferencing

### 1.2 Functional Block Diagram



Note: Not all peripherals are available at the same time due to multiplexing.



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**INSTRUMENTS** 

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## 2 Peripherals

**Table 2-1. Peripheral Description** 

Peripherals <sup>(1)</sup>	Peripherals <sup>(1)</sup> No Description				
EMIFB	1	32-Bit or 16-Bit SDRAM with 256MB address space.			
EMIFA	1	NOR, NAND (8-/16-Bit-Wide Data), 16-Bit SDRAM with 128MB address space.			
Flash Card Interface	1	Multi Media Cards (MMC), Secure Digital Cards (SD) and SDIO interfaces supported.			
EDMA3	1	32 independent DMA channels, 8 Quick DMA (QDMA) channels, 2 Transfer controllers, Programm transfer burst size (16/32/64 bytes).			
Timers	2	64-Bit General Purpose (configurable as 2 separate 32-bit timers, 1 configurable as Watch Dog).			
UART	3	One with RTS and CTS flow control			
SPI	2	Each with one hardware chip select, Master/Slave. Supports 3-, 4-, and 5- pin operation.			
I <sup>2</sup> C	2	Both Master/Slave. Supports up to 400 Kbps.			
Multichannel Audio Serial Port [McASP]	3	Each with transmit/receive, FIFO buffer, 16/12/4 serializers			
10/100 Ethernet MAC [EMAC] with Management Data I/O [MDIO]	1	RMII Interface			
Enhanced Pulse Width Modulator (ePWM)	3	6 Single Edge, 6 Dual Edge Symmetric, or 3 Dual Edge Asymmetric Outputs.			
Enhanced Capture Module [eCAP]	3	32-bit capture inputs or 3 32-bit auxiliary PWM outputs.			
Enhanced Quaduature Encoded Pulse Module [eQEP]	2	32-bit QEP channels with 4 inputs/channel.			
Universal Host Port Interface [UHPI]	1	16-bit multiplexed address/data			
USB 2.0	1	High-Speed OTG Controller with on-chip OTG PHY (supports Host, Device and OTG modes).			
USB 1.1	1	Full-Speed OHCI (as host) with on-chip PHY.			
General-Purpose Input/Output Port	1	Up to 128 GPIO pins			
LCD Controller	1	Supports low end 8-bit character based displays, mid-range, 1/4 VGA color, rasterized graphical displays and high end LCD display			
Real Time Clock [RTC]	1	32 KHz oscillator and seperate power rail. Provides time and date tracking and alarm capability.			
PLL Controller 0	1	Supplies the clocks to the DSP and most of the system peripherals.			

<sup>(1)</sup> Not all peripheral pins are available at the same time due to multiplexing.

# PRODUCT PREVIEW

### 3 Key Electrical Characteristics

INSTRUMENTS

			MIN	NOM	MAX	UNIT
CVDD	Supply voltage, (RVDD)	Core (CVDD, RTC_CVDD, PLL0_VDDA , USB0_VDDA12,	1.14	1.2 or 1.26	1.32	V
DVDD		/O, 1.8V (USB0_VDDA18, USB1_VDDA18)	1.71	1.8	1.89	V
		/O, 3.3V (DVDD, USB0_VDDA33, USB1_VDDA33)	3.15	3.3	3.45	V
VSS	Supply ground (\	VSS, USB0_VSSA33, USB0_VSSA, PLL0_VSSA, OSCVSS)	0	0	0	V
P <sub>Typ</sub>	Typical Power Consumption. Includes static and active power for both Core and I/O supplies	Use Case 1 : 300 MHz; DSP at 1.2 CVDD.		483 <sup>(1)</sup>		mW
T <sub>A</sub> Operating ambient temperature range		Default	0		70	°C
	temperature	A version	-40		105	°C
T <sub>J</sub> Operating junction temperature range		Default	0		90	
	temperature	A version	-40		125	°C
F <sub>SYSCLK1,6</sub> F	DSP Operating	-300 Device	0		300	MHz
	Frequency (SYSCLK1,6)	-200 Device	0		200	MHz

<sup>(1)</sup> These are preliminary pre-silicon design estimates and hence are subject to change.

### 3.1 Power Use Case Details

Use Case 1: At room temperature (25 °C) with the core voltage (CVDD) set to 1.2V. 70% DSP CPU utilization (300 MHz); EMIFB active at 50% utilization (133 MHz/16-bit); 25 MHz McASP Receive; SPI master at 50% utilization (27MHz); GPIOs at 50 utilization (33MHz). The actual current draw varies across manufacturing processes and is highly application-dependent.

### 4 Tools and Software Support

The supports the following tools and software:

- Code Composer Studio<sup>™</sup> 3.3
- DSP/BIOS™ 5.3
- DSP/BIOS<sup>™</sup> 5.3 based Peripheral Device Drivers
- DSP Chip Support Library (CSL)
- TMS320C6747 Development Kit

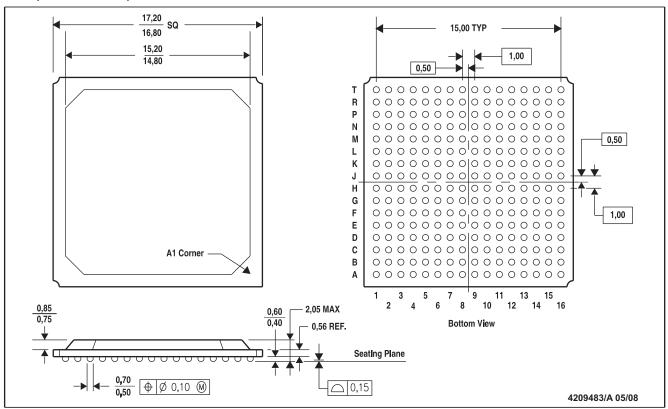
# Instruments

### **Mechanical Drawing**

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### ZKB (S-PBGA-N256)

### **PLASTIC BALL GRID ARRAY**



NOTES: All linear dimensions are in millimeters.

- This drawing is subject to change without notice.
- This is a lead-free solder ball design.

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